

Lead Free BGA Spheres Data Sheet

Rev: 2008/5/19 Ver.1

Model: PF684-S

No	Item	Specification
1	Alloy	Sn/Ag3.0/Cu0.5
2	Appearance	Bright and shiny surface finishes.
3	Shape	Sphere
4	Density	7.4 g/cm ³ (20°C)
5	Melting Point	217~219°C
6	Packing	125K、200K、250K、400K、500K、750K、1000K、1250K、1500K、2500K、4000K、7000K /Jars (Depends on size of spheres)
7	Feature	Produced by pure tin, silver and copper. Impurities are lowed to the minimum.
8	Application	For IC Package and BGA Rework.
9	Standard	According to JIS-Z-3282.
10	Storage and Handling Shelf life	Storage must be in a dry, non-corrosive and shine environment. Shelf life is 1 year from date of manufacture.

Diameters Tolerances

Diameters $\leq 0.25\text{mm}$	Grade A1	$\pm 5\mu\text{m}$
Diameters 0.30-0.45mm	Grade A2	$\pm 10\mu\text{m}$
Diameters 0.50-0.76mm	Grade A3	$\pm 20\mu\text{m}$

Alloy Composition

Sn	Ag	Cu	Zn	Al	Sb	Fe	As	Bi	Cd	Pb
REM.	2.8~	0.3~	0.001	0.001	0.05	0.02	0.03	0.10	0.002	0.05
	3.2	0.7	MAX	MAX	MAX	MAX	MAX	MAX	MAX	MAX

Patent No.: Japanese Patent No. 3296289 U.S Patent No. 6179935B1. Germany Patent No.19816671C2.

All alloy of SHENMAO' products were to conform to SONY Green Partner and comply RoHS requirement.



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